



Material Content Data Sheet



Sales Product Name		TLE42744G V33		Issued		2. August 2018		
MA#		MA000736806						
Package		PG-TO263-3-1		Weight*		1598.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.179	0.20	0.20	1988	1988
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		57	
	non noble metal	iron	7439-89-6	0.304	0.02		190	
	non noble metal	copper	7440-50-8	304.026	19.02	19.05	190151	190398
	non noble metal	aluminium	7429-90-5	0.171	0.01	0.01	107	107
wire	non noble metal	aluminium	7429-90-5	0.171	0.01	0.01	107	107
encapsulation	organic material	carbon black	1333-86-4	1.456	0.09		911	
	plastics	epoxy resin	-	66.978	4.19		41891	
	inorganic material	silicondioxide	60676-86-0	659.586	41.25	45.53	412532	455334
leadfinish	non noble metal	tin	7440-31-5	9.657	0.60	0.60	6040	6040
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	143	144
solder	non noble metal	tin	7440-31-5	0.096	0.01		60	
	noble metal	silver	7440-22-4	0.120	0.01		75	
	non noble metal	lead	7439-92-1	4.597	0.29	0.31	2875	3010
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		103	
	non noble metal	iron	7439-89-6	0.548	0.03		343	
	non noble metal	copper	7440-50-8	547.666	34.25	34.29	342533	342979
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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